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PHOTOCOUPLER PS2381-1

4-PIN LSOP PHOTOCOUPLER OPERATING AMBIENT TEMPERATURE 115°C

-NEPOC Series-

DESCRIPTION

The PS2381-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor.

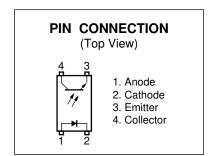
This package is mounted in a plastic 4-LSOP (<u>Long Mini-Flat Small Qutline Package</u>) for high density applications. The package has shield effect to cut off ambient light.

FEATURES

- Operating ambient temperature: 115°C
- · Isolation distance (0.4 mm MIN.)
- High isolation voltage (BV = 5 000 Vr.m.s.)
- · 4-pin LSOP (Long Mini-Flat Small Outline Package) type
- High-speed switching ($t_r = 4 \mu s$ TYP., $t_f = 5 \mu s$ TYP.)
- Embossed tape product: PS2381-1-F3: 3 000 pcs/reel
- Pb-Free product
- · Safety standards
 - UL approved: No. E72422
 - CSA approved: No. CA 101391 (CA5A, CAN/CSA-C22.2 60065, 60950)
 - SEMKO approved: No. 911049
 - DIN EN60747-5-2 (VDE0884 Part2) approved: No. 40028917 (Option)
 - CQC approved: CQC10001041058 for GB4943-2001
 CQC10001041059 for GB8898-2001

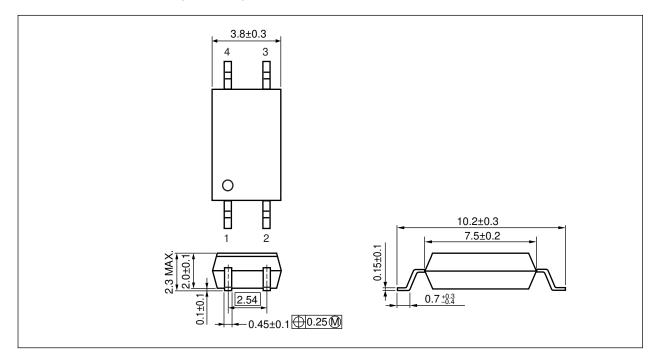
APPLICATIONS

- · Power supply
- FA/OA equipment



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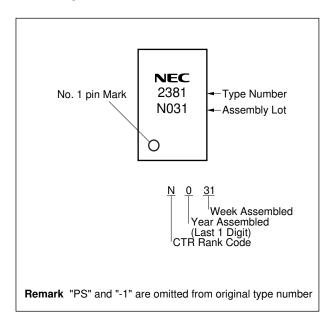
PACKAGE DIMENSIONS (Unit: mm)



PHOTOCOUPLER CONSTRUCTION

Parameter	Unit (MIN.)		
Air Distance	8 mm		
Outer Creepage Distance	8 mm		
Isolation Distance	0.4 mm		

MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification etc.	Packing Style	Safety Standard Approval	Application Part Number *1
PS2381-1	PS2381-1Y-AX	Pb-Free and	20 pcs (Tape 20 pcs cut)	Standard products	PS2381-1
PS2381-1-F3	PS2381-1Y-F3-AX	Halogen Free	Embossed Tape 3 000 pcs/reel	(UL, CSA, SEMKO	
				approved)	
PS2381-1-V	PS2381-1Y-V-AX		20 pcs (Tape 20 pcs cut)	DIN EN60747-5-2	
PS2381-1-V-F3	PS2381-1Y-V-F3-AX		Embossed Tape 3 000 pcs/reel	(VDE0884 Part2)	
				Approved (Option)	

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

	Parameter	Symbol	Ratings	Unit
Diode	Forward Current (DC)	lF	60	mA
	Reverse Voltage	VR	6	٧
	Power Dissipation Derating*1	⊿P₀/°C	1.0	mW/°C
	Power Dissipation	PD	100	mW
	Peak Forward Current*2	IFP	1.5	Α
Transistor	Collector to Emitter Voltage	Vceo	80	٧
	Emitter to Collector Voltage	Veco	7	٧
	Collector Current	lc	50	mA
	Power Dissipation Derating*1	⊿Pc/°C	1.5	mW/°C
	Power Dissipation	Pc	150	mW
Isolation Voltage ^{*3}		BV	5 000	Vr.m.s.
Total Power Dissipation		Рт	250	mW
Operating Ambient Temperature		TA	-40 to +115	°C
Storage Temperature		T _{stg}	-40 to +125	°C

^{*1} Derating from $T_A = 25^{\circ}C$.

^{*2} PW = 100 μ s, Duty Cycle = 1%

^{*3} AC voltage for 1 minute at $T_A = 25^{\circ}C$, RH = 60% between input and output. Pins 1-2 shorted together, 3-4 shorted together.

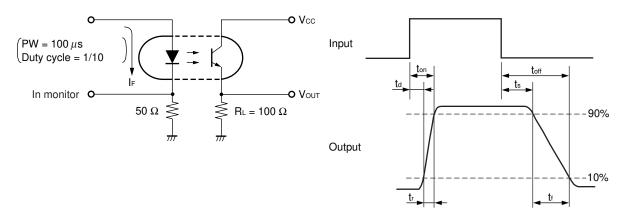
ELECTRICAL CHARACTERISTICS (TA = 25°C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	I _F = 5 mA		1.1	1.4	٧
	Reverse Current	lR	V _R = 5 V			5	μА
	Terminal Capacitance	Ct	V = 0 V, f = 1 MHz		15		pF
Transistor	Collector to Emitter Dark Current	Iceo	IF = 0 mA, VcE = 24 V			100	nA
Coupled	Current Transfer Ratio	CTR	IF = 5 mA, VCE = 5 V	50	100	400	%
	(lc/l _F)*1		IF = 1 mA, VCE = 5 V	10	50		
	Collector Saturation Voltage	VCE (sat)	IF = 10 mA, Ic = 2 mA			0.3	V
	Isolation Resistance	R _{I-O}	Vi-o = 1 kVpc	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.4		pF
	Rise Time*2	t r	$Vcc = 5 \text{ V}, \text{ Ic} = 2 \text{ mA}, \text{ RL} = 100 \Omega$		4		μs
	Fall Time*2	t f			5		

*1 CTR rank

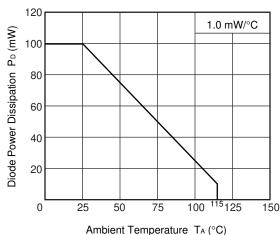
CTR rank	CTR (%)	Conditions
W	130 to 260	IF = 5 mA, VCE = 5 V
	20 to	IF = 1 mA, VCE = 5 V
L	100 to 300	IF = 5 mA, VCE = 5 V
	20 to	IF = 1 mA, VCE = 5 V
М	50 to 150	IF = 5 mA, VCE = 5 V
	10 to	IF = 1 mA, VCE = 5 V
N	50 to 400	IF = 5 mA, VCE = 5 V
	10 to	IF = 1 mA, VcE = 5 V

*2 Test circuit for switching time

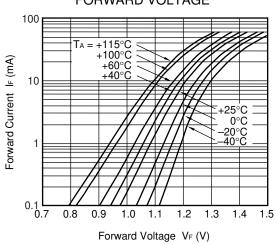


TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)

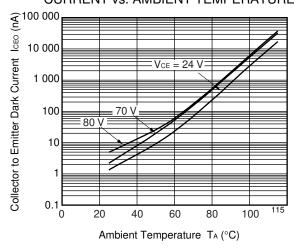




FORWARD CURRENT vs. FORWARD VOLTAGE

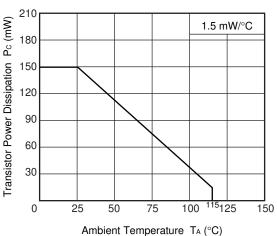


COLLECTOR TO EMITTER DARK **CURRENT vs. AMBIENT TEMPERATURE**

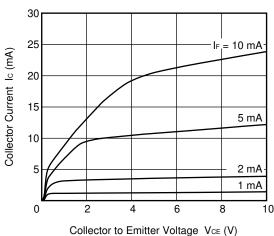


Remark The graphs indicate nominal characteristics.

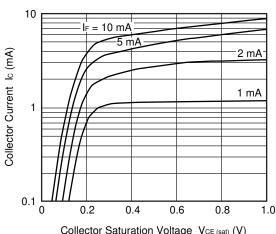
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE

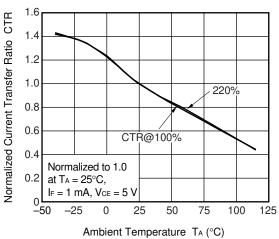


COLLECTOR CURRENT vs. **COLLECTOR SATURATION VOLTAGE**

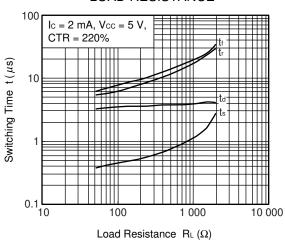


Collector Saturation Voltage VcE (sat) (V)

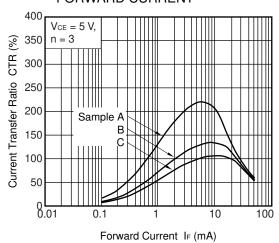
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



SWITCHING TIME vs. LOAD RESISTANCE

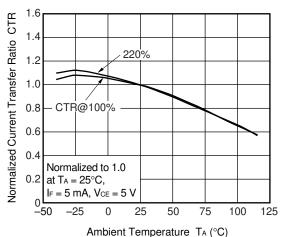


CURRENT TRANSFER RATIO vs. FORWARD CURRENT

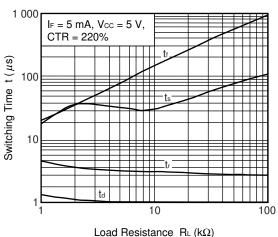


Remark The graphs indicate nominal characteristics.

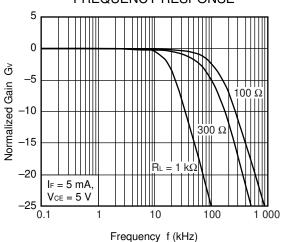
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



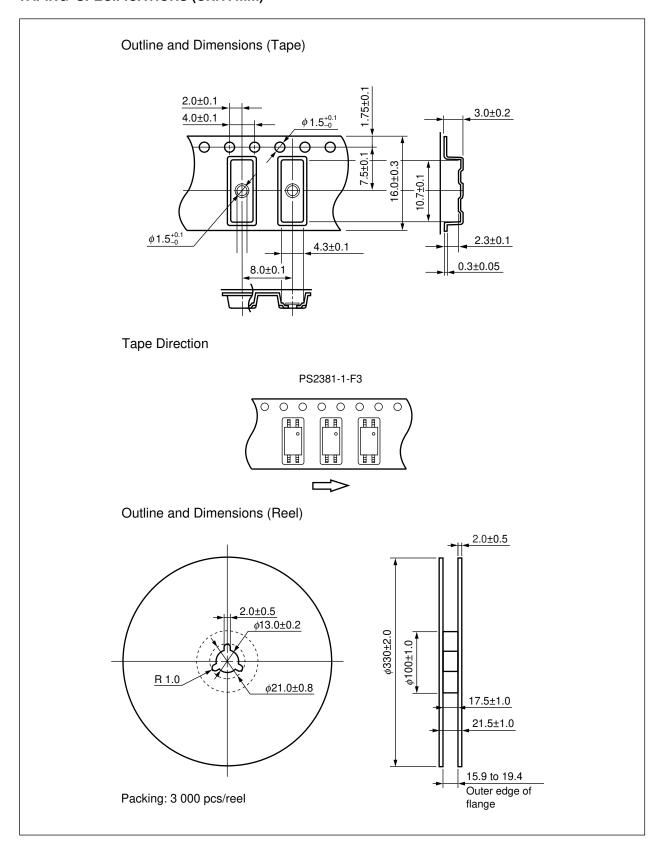
SWITCHING TIME vs. LOAD RESISTANCE



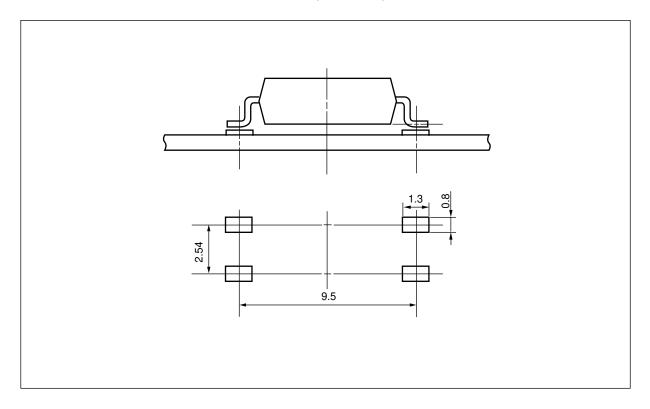
FREQUENCY RESPONSE



TAPING SPECIFICATIONS (UNIT: mm)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Remark All dimensions in this figure must be evaluated before use.

NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

Peak reflow temperature
 260°C or below (package surface temperature)

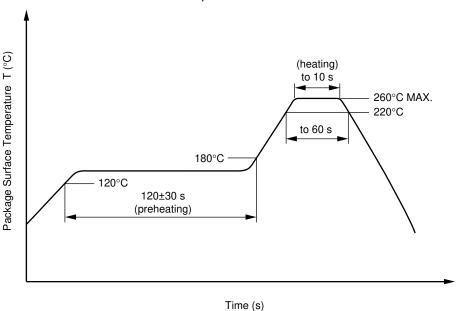
Time of peak reflow temperature
 Time of temperature higher than 220°C
 10 seconds or less
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Three

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

• Preheating conditions 120°C or below (package surface temperature)

Number of times
 One (Allowed to be dipped in solder including plastic mold portion.)

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

(3) Soldering by soldering iron

Peak temperature (lead part temperature)
 Time (each pins)
 350°C or below
 3 seconds or less

Flux
 Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Spec.	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		40/115/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.5 \times U_{\text{IORM}}, P_{\text{d}} < 5 \text{pC}$	UIORM Upr	1 130 1 695	V _{peak} V _{peak}
Test voltage (partial discharge test, procedure b for all devices) $U_{pr} = 1.875 \times U_{IORM}, P_d < 5 \; pC$	Upr	2 119	$V_{\sf peak}$
Highest permissible overvoltage	Utr	8 000	V _{peak}
Degree of pollution (DIN EN 60664-1 VDE0110 Part 1)		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303 Part 11))	CTI	175	
Material group (DIN EN 60664-1 VDE0110 Part 1)		III a	
Storage temperature range	T _{stg}	-40 to +125	°C
Operating temperature range	TA	-40 to +115	°C
Isolation resistance, minimum value VIO = 500 V dc at TA = 25°C VIO = 500 V dc at TA MAX. at least 100°C	Ris MIN. Ris MIN.	10 ¹² 10 ¹¹	Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current I _F , Psi = 0) Power (output or total power dissipation) Isolation resistance	Tsi Isi Psi	175 400 700	°C mA mW
V _{IO} = 500 V dc at T _A = Tsi	Ris MIN.	10 ⁹	Ω

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M8E0904E

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
- Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.